

Title (en)  
Connecting element and method of manufacturing a connecting element

Title (de)  
Verbindungselement und Verfahren zur Herstellung eines Verbindungselements

Title (fr)  
Élément de connexion et procédé de fabrication d'un élément de connexion

Publication  
**EP 2763243 B1 20170607 (EN)**

Application  
**EP 13153250 A 20130130**

Priority  
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Abstract (en)  
[origin: EP2763243A1] The invention relates to a connecting element (100) for establishing an electrically conductive connection between two further elements (200, 300), particularly for connecting a body unit (200) of a grounding kit (1000) with a grounding element (300), wherein said connecting element (100) comprises at least two layers (102a, 102b) of electrically conductive material, wherein at least two layers (102a, 102b) comprise different material.

IPC 8 full level  
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CPC (source: EP)  
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Citation (examination)  
• EP 2398112 A1 20111221 - ALCATEL LUCENT [FR]  
• WO 2007049834 A1 20070503 - KIM KUI-YEUN [KR]

Cited by  
EP3490071A1; CN109994845A

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AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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